





TRAY STACKING DETAIL

JEDEC	TITLE: THIN MATRIX TRAY FOR	ISSUE	DATE		SHEET
SOLID STATE PRODUCT OUTLINE	SHIPPING AND HANDLING OF ADVANCED MEMORY BUFFER	А	MAR 2006	CO-035	2 OF 5

VARIAT	TON DIMENSIONS ARE IN	 1 MIL	LIMETE	.KS		
VARIATION	PACKAGE BODY SIZE			TRAY MATRIX		
AA	19.5MM X 24.5MM			10		
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<u>VARIATIONS</u>

N Y M M O L	DIMENSIONS ARE IN MILLIMETERS MIN NOM MAX	ZOHE		
М	24.15 BSC	14		
M1	26.10 BSC			
М2	29.20 BSC			
М3	29.20 BSC			
Ν	655			
N1	4 COLUMNS			
N2	10 ROWS			
N3	40			
N4	19.5 MM X 24.5 MM			
N5	ROW/COLUMN [2/2], [9/3]			
N6	ROW/COLUMN [5/2.3], [6/2,3]			
NOTES	9, 10, 11, 14, 20			
REF.	5-736			
ISSUE				

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NOTES:



THESE SURFACES TO BE FREE OF SEAMS.



CHAMFER DENOTES PACKAGE PIN 1 ORIENTATION.

3. TRAY VACUUM PICKUP METHOD ALLOWS TWO SEPARATE PICKUP AREAS, RESULTING IN TWO CLOSED CELLS PER TRAY. OPTIONAL VACUUM PICKUP CELL LOCATIONS ARE N5.



TRAY VACUUM PICKUP METHOD REQUIRES A 28 mm SQUARE (MINIMUM) WALLED PICKUP AREA, LOCATED AS CLOSE TO THE CENTER OF THE TRAY AS IS PRACTICAL. CENTER VACUUM PICKUP CELL LOCATIONS ARE N6.



THE SCALLOP ALLOWS THE USE OF A PIN TO MECHANICALLY BIAS THE TRAY ORIENTATION.

- 6. N REFERS TO THE PACKAGE LEADCOUNTS SUPPORTED, FULLY POPULATED ARRAY.
- 7. TOTAL USABLE CELLS $N3 = N1 \times N2$.
- 8. PACKAGE INTERFACE CONTROLLED BY PACKAGE DESIGN AND LEAD FORM.
- 9. NONTABULATED DIMENSIONS HAVE A TOLERANCE OF $.X = \pm 0.25$, $.XX = \pm 0.13$, ANGLES $\pm 0.5^{\circ}$.
- 10. ALL DIMENSIONS ARE IN MILLIMETERS.
- 11. INTERPRET DIMENSIONS AND TOLERANCES IN ACCORDANCE WITH ASME Y14.5M-1994



XXX IS THE MAXIMUM OPERATING TEMPERATURE THE EMPTY TRAY CAN BE SUBJECTED TO FOR 48 CONTINUOUS HOURS WITHOUT VIOLATING THE DIMENSIONAL TOLERANCE OF THE TRAY.



13\ N4 INDICATES THE PACKAGE TYPE ACCOMODATED.

14. DIMENSIONS M, M1, M2, AND M3 DEFINE THE CENTER LINES FOR THE CELL SITES.



15\ BOTTOM SIDEWALL NOTCHES REQUIRE A 2.00 mm (MINIMUM) DEPTH TO FACILITATE AUTO HANDLING EQUIPMENT.

- 16. ALL EXTERNAL TRAY SURFACES THAT MAY COME IN CONTACT WITH THE DRY PACK BAGS SHALL BE FREE OF SHARP EDGES.
- 17. ALL TRAY MEASUREMENTS ARE TO BE MADE WITH THE TRAY UN-RESTRICTED.
- 18. RECOMMENDED FOR PACKAGES WITH OVERALL THICKNESS OF 4.75 mm OR LESS
- 19. VACUUM CELL LOCATIONS ARE IN THE FREE AREAS DOWN THE CENTER OF THE TRAY, NOT IN THE POCKET AREAS.
- 20. TO BE USED ONLY FOR ADVANCED MEMORY BUFFER DEVICE USING PACKAGE PER MO-261 BY SPECIAL DISPENSATION OF THE JC-11-COMMITTEE.

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